

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Koji Watanabe et al.

Application No.: 10/541,586

Confirmation No.: 1996

Filed: September 30, 2005

Art Unit: 1796

For: CURING RESIN COMPOSITION,
ADHESIVE EPOXY RESIN PASTE,
ADHESIVE APOXY RESIN SHEET,
CONDUCTIVE CONNECTION PASTE,
CONDUCTIVE CONNECTION SHEET,
AND ELECTRONIC COMPONENT JOINED
BODY

Examiner: M. J. Feely

SUBMISSION OF CORRECTED INFORMATION DISCLOSURE STATEMENT (IDS)
AND REQUEST FOR REFUND

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Madam:

Applicants note that the Information Disclosure Statement was filed on April 15, 2009, indicated that it was filed “after the mailing date of a Final Office Action or Notice of Allowance, whichever occurred first, but on or before payment of the Issue Fee.” However, this Information Disclosure Statement was actually filed after issuance of a first Office Action in this application, but prior to a Final Office Action or Notice of Allowance. Also, it was submitted within three three month period pursuant to 37 C.F.R. 1.97(e)(2). Therefore, applicants submit herewith a corrected Information Disclosure Statement to replace the Information Disclosure Statement filed April 15, 2009.

Also, applicants request a refund of the government fee in the amount of \$180.00 as this fee was not necessary to facilitate this filing. The Director is hereby authorized to credit the undersigned's deposit account number 22-0185 in the amount of \$180.00.

Dated: May 11, 2009

Respectfully submitted,

Electronic signature: /Burton A. Amernick/
Burton A. Amernick

Registration No.: 24,852
CONNOLLY BOVE LODGE & HUTZ LLP
1875 Eye Street, NW
Suite 1100
Washington, DC 20006
(202) 331-7111
(202) 293-6229 (Fax)
Attorney for Applicant